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(54) Title: MOLDED FLEX CIRCUIT BALL GRID ARRAY AND METHOD OF MAKING

(57) Abstract

A grid array assembly method and apparatus uses a flex circuitry substrate and includes providing a series of conforming flex circuitry substrates (201), the flex circuitry substrates include bonding pads (205) and metallization on a first surface and, holes in the substrate which define a contact pad array on the opposite surface. The substrates are tested and accepted, then mounted on a carrier strip (31) with longitudinally aligned apertures. The carrier strip is typically a metal such as copper. The strip with mounted substrates is then passed to a station where an IC die (41) is mounted on the substrate first surface, wire bonds (701) are placed from the die to the bonding pads, and the assembly is encapsulated (61) by auto-molding to form a package body. Subsequently, interconnecting bumps (211) are placed on the contact pads and the assembly is removed from the strip.